

Utilizing foundries to scale hybrid electro-optic polymer modulators

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Ringing the Bell at NASDAQ (10th Sept 2021) LIGHTWAVE











Organic up-list...as promised in 2017...

NASDAQ 1yr Anniversary





1st Sept 2022: 1yr on NASDAQ

Source: NASDAQ: LWLG • 5



Takeaways

- •We have unique polymers...
- Our technology is ultra-fast, ultra-low power...
- We are positioned to have polymers become ubiquitous...
- Polymers are foundry compatible...



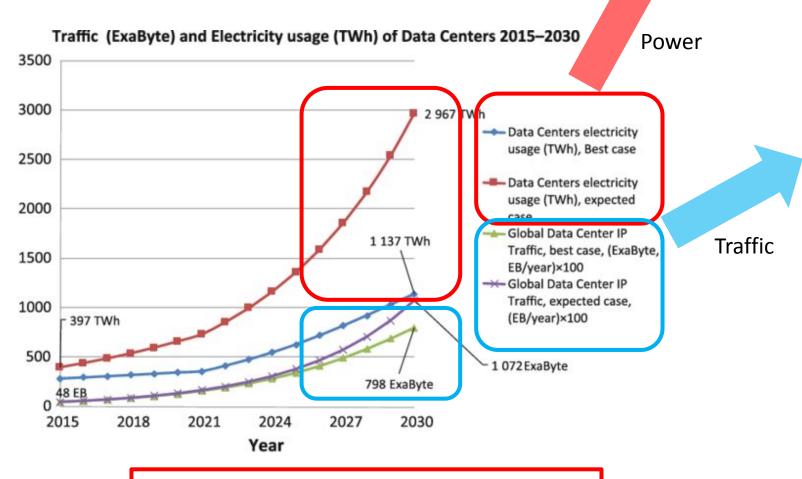
- Naturally very fast at switching light (material properties)
 - 2-3X existing solutions using modulators
- Naturally very low power consuming (material properties)
 - 10X lower power depending on device/architectural design
- Easily fabricated using CMOS/Silicon foundries
 - Process is standard and does not require special tool kits
 - Consistent, stable and reliable poling process
- EO Polymer has security of supply and scalable in vol
 - Material designed and sourced directly from LWLG
- Low-cost addition to integrated photonics platforms
 - Silicon photonics can be boosted in performance





...Yet Power Consumption Spiraling Up

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Major challenge for DCs and service providers

Power is growing exponentially with increased traffic levels...it is the Achilles Heel...

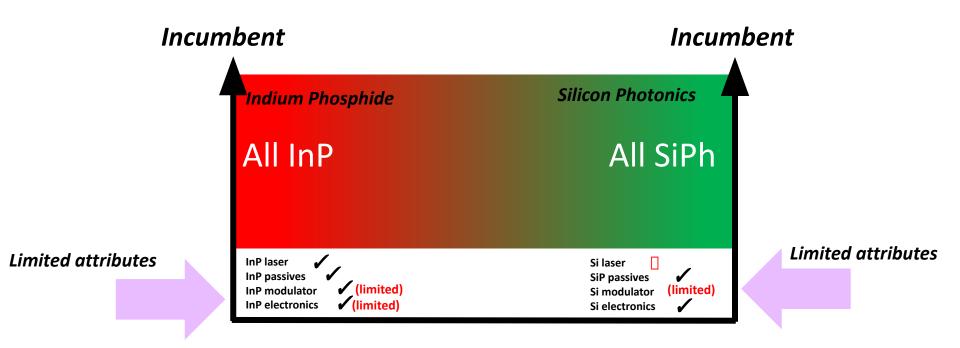
Source: Publication: Walnum, HJ et al NASDAQ: LWLG • 11



Fiber communications have 2 incumbent PICs, however...



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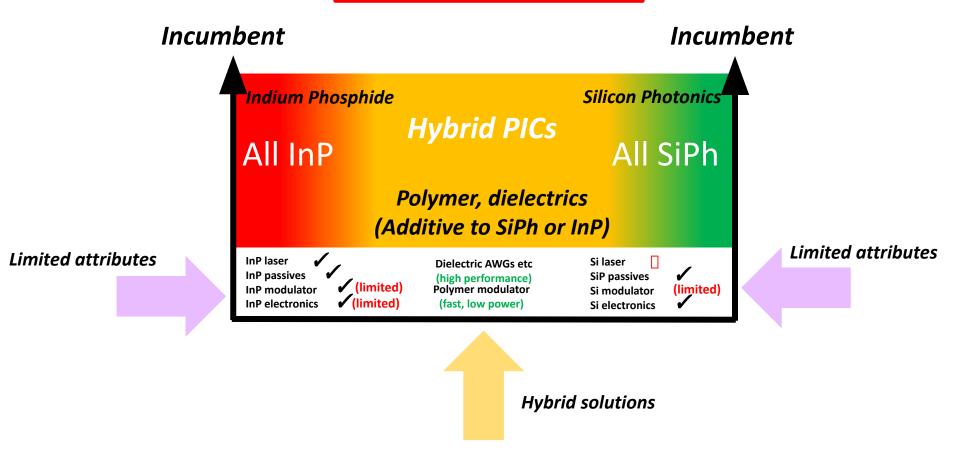


Source: LWLG • 13

Hybrid PICs increase performance...



New hybrid PICs



Hybrid PICs can boost performance of PICs

Source: LWLG • 14

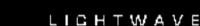
Trend towards hybrid PICs...



- PIC incumbent platforms:
 - InP (Indium Phosphide) □ e.g. Hybrid PIC □ InP + Si ICs
 - SiPh (Silicon photonics) □ e.g. Hybrid PIC □ SiPh + InP Laser
 - GaAs (Gallium Arsenide) □ e.g. Hybrid PIC □ GaAs + Si ICs

New platforms for Hybrid PICs

- Polymers (modulators)
- Dielectrics (passives)
- Silica (passives)
- Glass (passives)
- Thin Film Lithium Niobate (TFLN) (modulator)
- Metal/plasmonic, (modulator)
- Barium titanate (BTO) (modulator)
- Germanium (detector)
- Gallium Nitride (GaN) (LEDs)
- Many others...



Representative PIC actors...

- Growth of Silicon photonics
- Trend towards hybrid platforms for PICs
- What combinations of technology make sense for *hybrid* PICs?



Challenge is to further PIC performance with other materials □ **hybrid PICs**

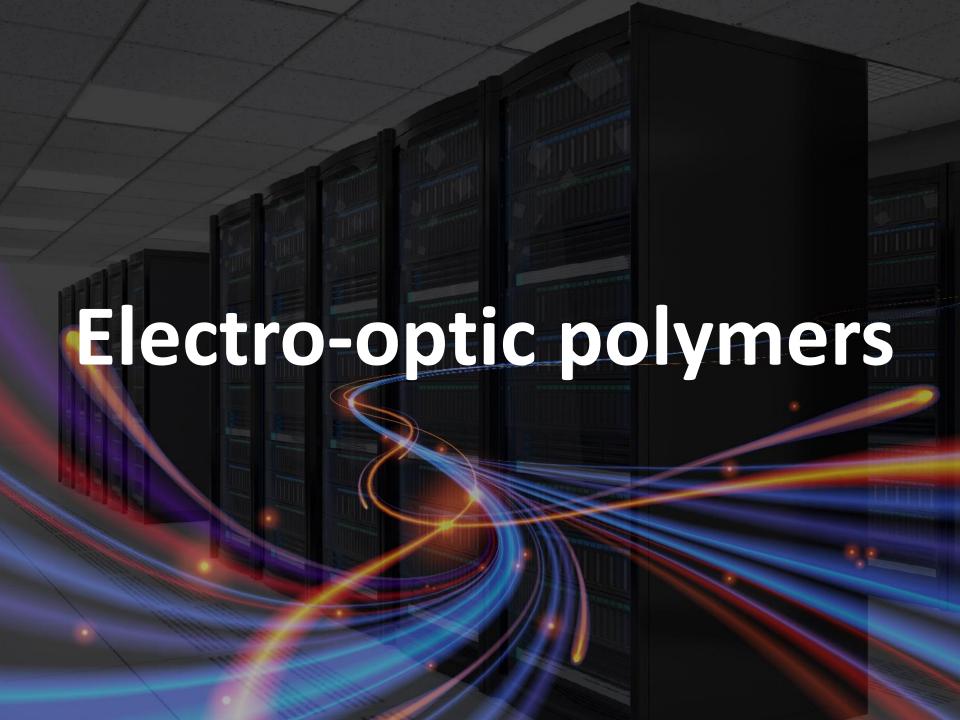
Source: Yole NASDAQ: LWLG • 16



Foundry compatibility for PICs

New technology	Foundry compatibility
Polymers (modulators)	Silicon, InP, GaAs, others
Dielectrics (passives)	Silicon, InP, GaAs, others
Silica (passives)	Silicon, InP, GaAs, others
Glass (passives)	Silicon, InP, GaAs, others
Thin Film Lithium Niobate (modulators)	LiNoB, silicon (?)
Metal/plasmonic (modulators)	Silicon, InP, others
Barium Titanate (modulators)	Silicon (?)
Germanium (detectors)	Silicon, GaAs
Gallium Nitride (LEDs, lasers)	GaN, silicon (?)
Graphene (detectors)	Silicon (?)

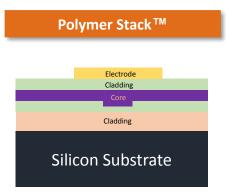
Silicon and InP offers best opportunities to scale volume quickly and efficiently



Natural integration with big foundries

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Additive to semiconductor platforms (SiPh, InP...) to enhance performance

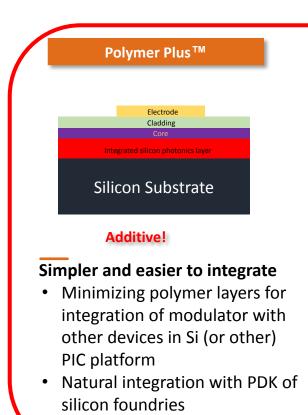


Polymer stack modulator

3-layer polymer stack waveguides

Classic!

- Excellent high-speed performance and high stability.
- Standard fab equipment & methods



Polymer Slot™

Electrode
Silicon slot layer

Silicon Substrate

Polymers in Si slot modulators

Tiny!

- Small size for highest integration levels
- Natural integration with PDK of silicon foundries

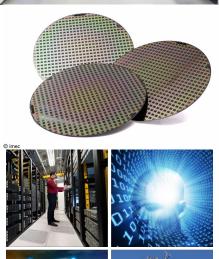


Partnering for success

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- Partnering with multiple foundries, packaging partners and module/transceiver partners to position LWLG for future high-volume production
- Partnering to qualify polymer Process
 Development Kits (PDK) with foundries using standard fabrication techniques
- Technology evaluation & feedback
- Partnering for licensing the use of polymer materials that have been sourced, supplied and manufactured by LWLG
- Partnering for technology transfer of fabrication and device design to manufacturing facilities and foundries









Partnering allows us to focus on our uniqueness, efficient use of capital, & to prepare for volume...

Source: Global Foundries, IMEC NASDAQ: LWLG • 22

Volume scale with silicon foundries with timelines

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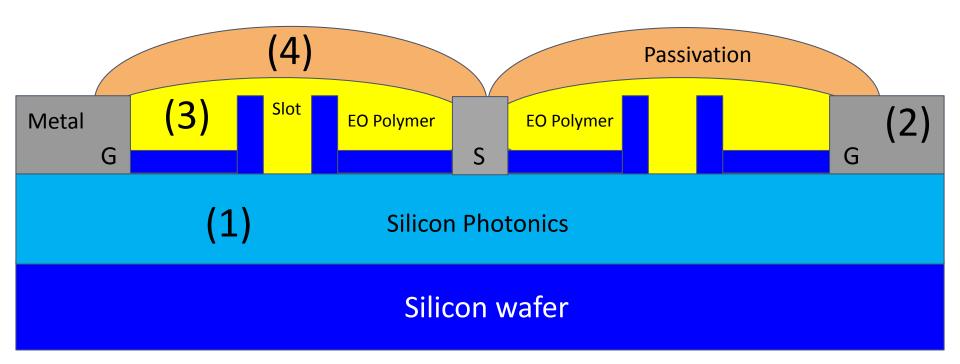
Foundry	Geographical location	Wafers	Existing PIC PDK (silicon photonics, InP)	Open to create EO polymer PDK	Expected results
Foundry A (polymer plus)	North America	Silicon	Yes	In progress	2H22-1H23
Foundry B (polymer plus)	North America	Silicon	Yes	In progress	2H22-1H23
Foundry C (polymer plus)	Europe	Silicon	Yes	In progress	2H22-1H23
Foundry D (polymer slot)	North America	Silicon	Yes	In progress	2H22
Foundry E (polymer slot)	Europe	Silicon	Yes	In progress	2H22
Foundry F (polymer slot) – in discussion	North America	Silicon	Yes	Planned	2023
Foundry G (polymer slot) – in discussion	Europe	InP	Yes	Planned	2023

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CMOS/silicon compatible PDK ☐ Polymer Slot ™

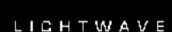


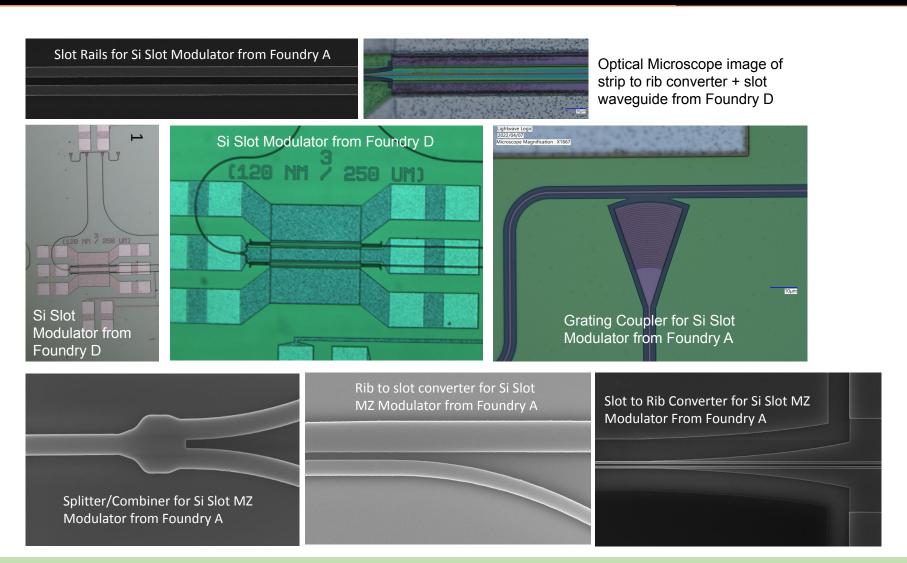
- (1) Standard CMOS/silicon photonics chip with slots defined by photolithography
- (2) Standard metallization for gate/source contacts
- (3) Spin-on EO polymer, cured in standard ovens, polled for optical switching
- (4) Dielectric passivation for protection to environment (chip-scale packaging)
- (5) Standardized, consistent poling process with extremely high yields



Standard silicon fabrication processes; standard silicon tools

Foundry fabrication with PDK

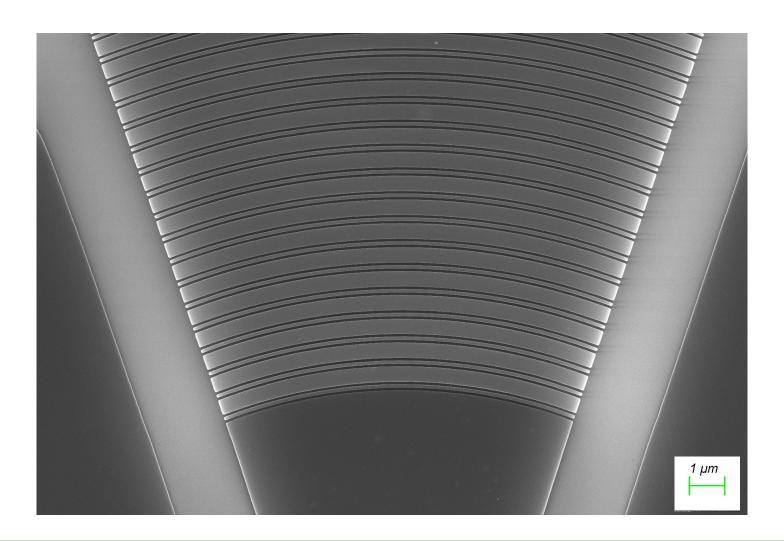




Standard silicon fabrication components...







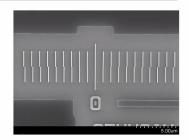
Vertical grating coupler example

Polymer slot – foundry processing

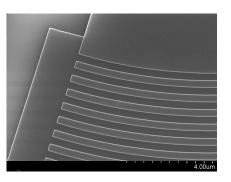


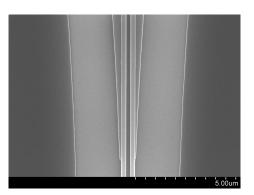
Pilot Wafer SEM Images





Verniers: better than 20 nm alignment

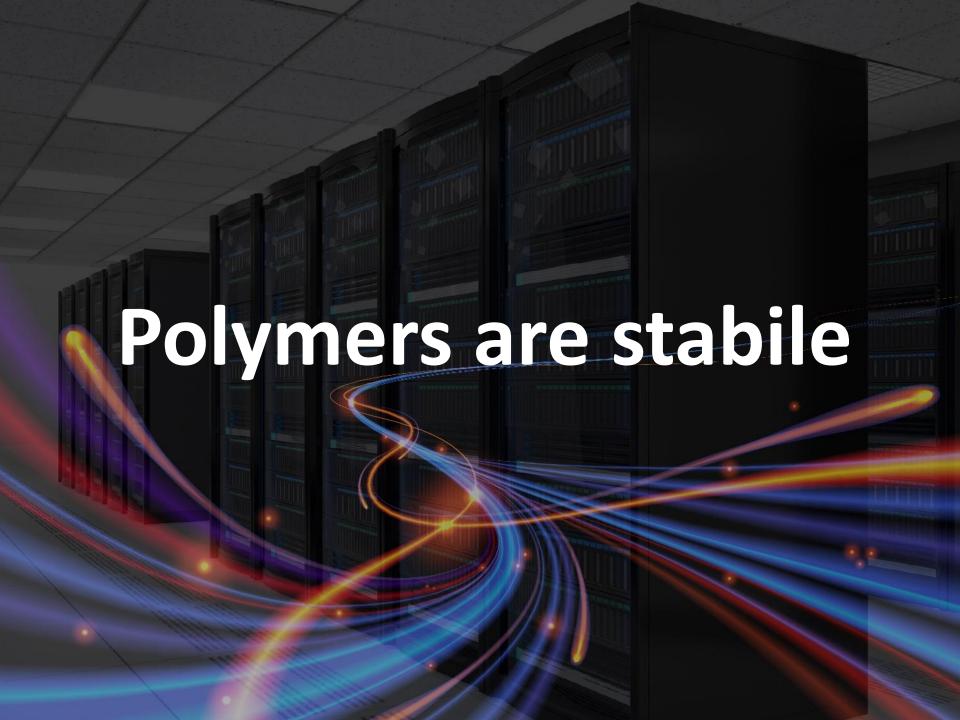




Grating Couplers and straight waveguides with good (standard) roughness and Strip-to-slot converters with good definition

Poling for foundries

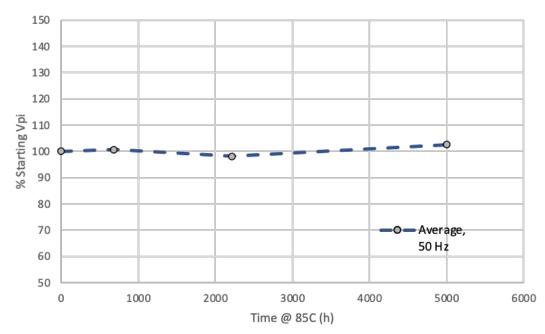
- Unique EO performance of poled polymers
 - For example: Bandwidths in excess of 100GHz, phase velocity match allowing bandwidths of 170GHz+, Low Vpi, High r33...
- Polymers are stable and reliable
 - The same arguments were made against LCDs and OLEDs and now we use OLED TVs, mobile displays....and we never discuss stability, reliability issues today...ever...
- Today, poling is a process that is consistent, stable and reliable and suitable for foundry operation
 - Advanced process, excellent control, standardized technique
 - Extremely high yields on >1000 poled devices...



Stability of polymers

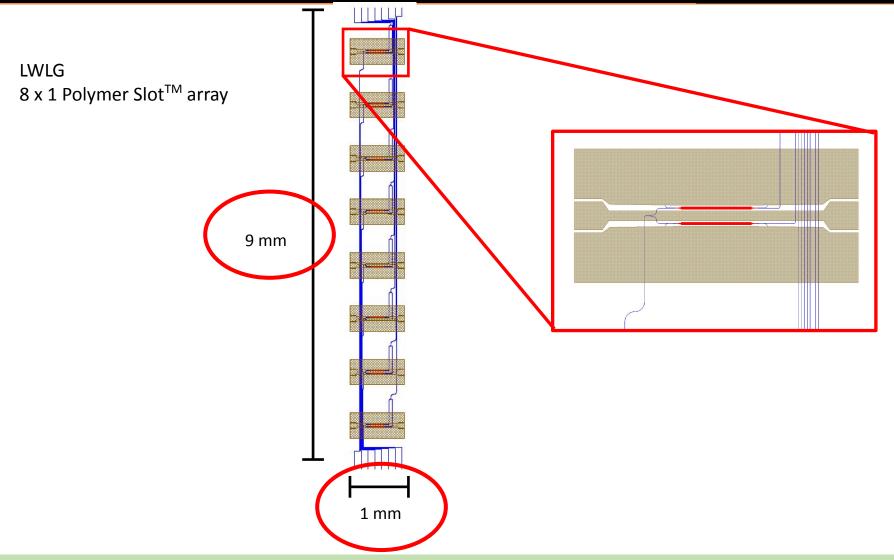
- 3 layer-stack devices
- Over 5khrs stability @ 85C
- Voltage delta
 <5% @ 1kHz for continuous change

die V_{π} @ 50Hz vs 85C storage time





Polymer slot modulators are very small LICHTWAVE

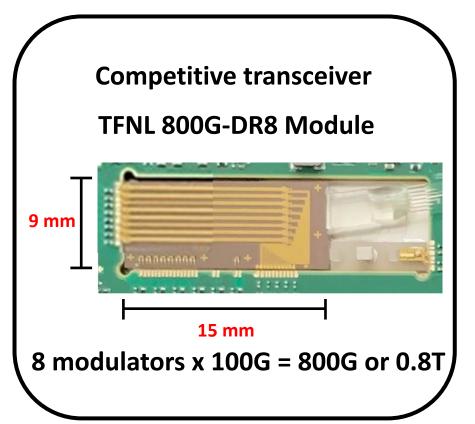


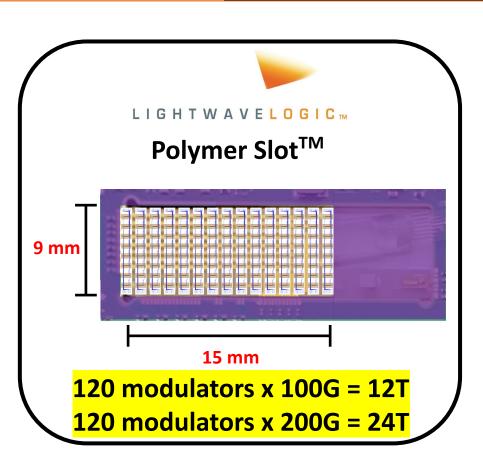
Size matters!

Source: Lightwave Logic (LWLG)

NASDAQ: LWLG • 32

Only 30X better*...





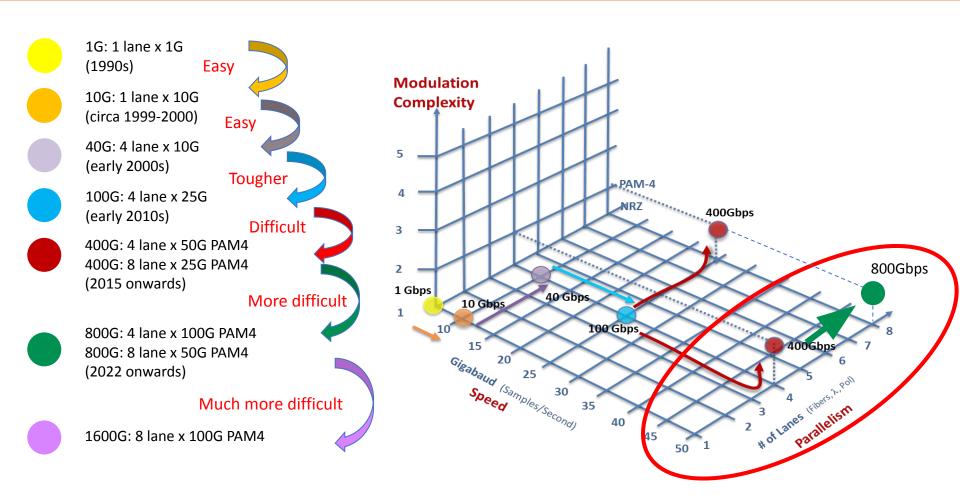
Potential for 30x data capacity in same pluggable formfactor

At least 30X better than competition...size, low power, and speed matter...



Historical perspective





Increasing data rates becomes more and more difficult...

Traffic capacity: road analogy

Good roads: Faster cars: more traffic capacity



More lanes: more traffic capacity



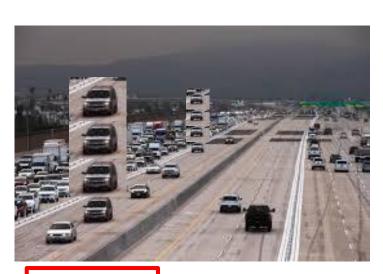
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Traffic handling: road analogy



What about speed?

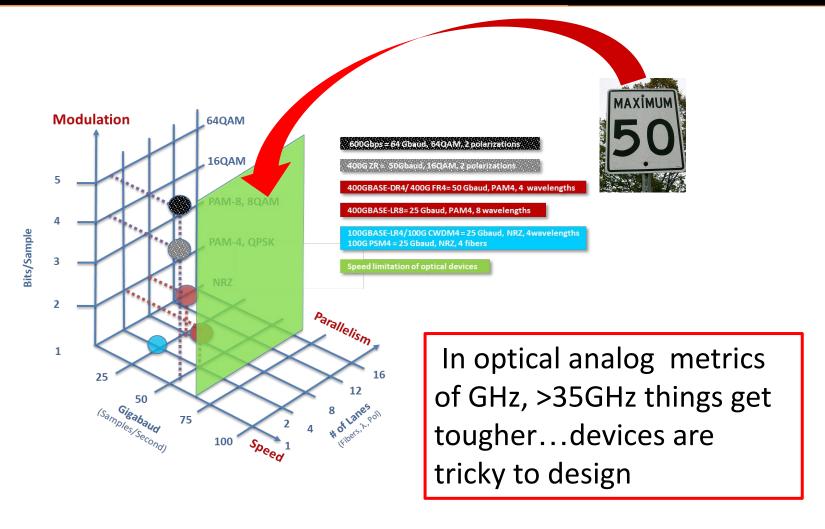




Still ~60 mph

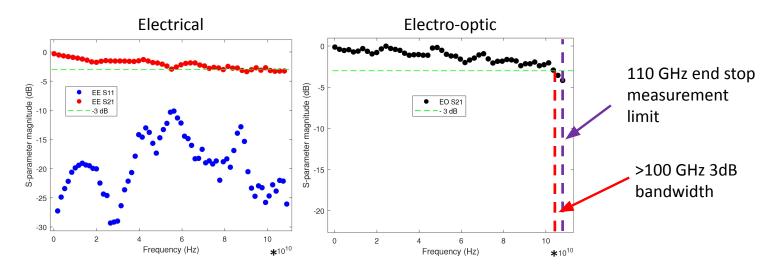
Speed limited by conventional photonics





Speed limited in optical devices by device physics...requires innovation...

Recent high-frequency S-parameter data from polymer modulators



Ultra-fast polymers break the speed limit...







The holy grail....single lane

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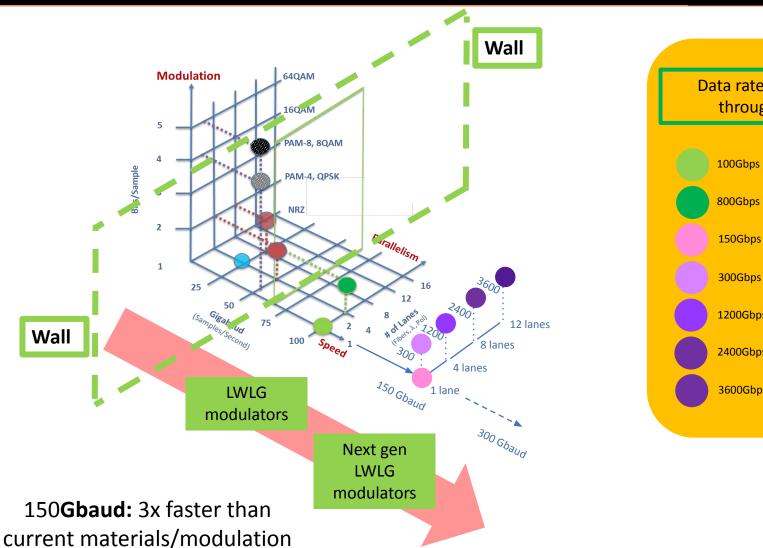
PATH TO SINGLE LANE



Single lane...have to have faster optics...

Our polymers break through the speed wall





Data rates after breaking through the wall...

100Gbps = 100Gbaud, NRZ, 1 lane

800Gbps = 100Gbaud, PAM4, 4 lanes

150Gbps = 150Gbaud, NRZ, 1 lane

300Gbps = 150Gbaud, PAM4, 1 lane

1200Gbps = 150Gbaud, PAM4, 4 lanes

2400Gbps = 150Gbaud, PAM4, 8 lanes

3600Gbps = 150Gbaud, PAM4, 12 lanes

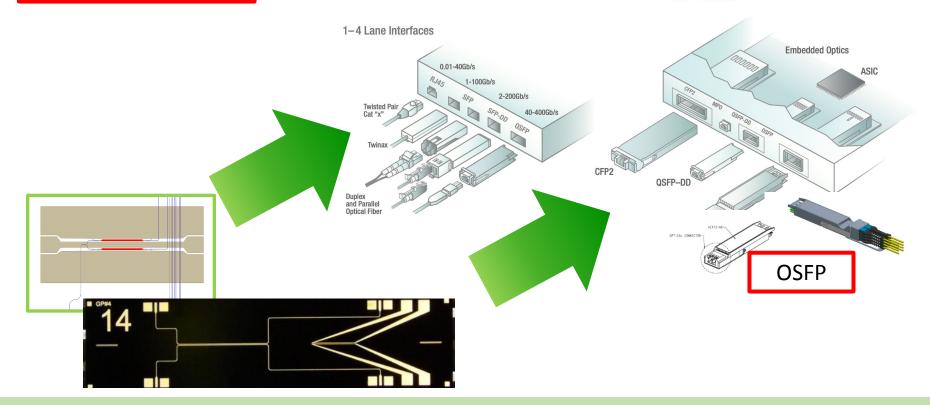
Polymer modulators fabricated in silicon foundries

FORM FACTORS

This diagram shows the most common form factors used in Ethernet ports. Hundreds of millions of RJ45 ports are sold a year while tens of millions of SFP and millions of QSFP ports ship a year.

This diagram shows new form factors initially designed for 100GbE and 400GbE Ethernet ports.

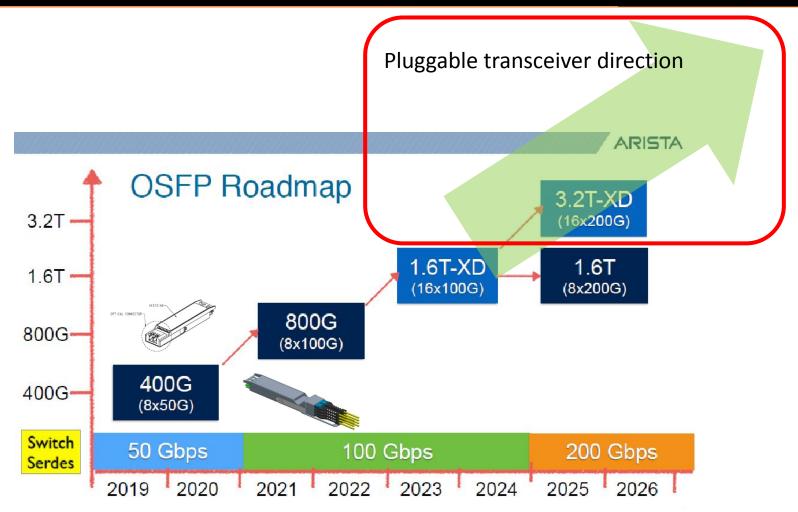
4+ Lane Interfaces



Polymer engines for pluggable transceivers

Optical transceiver trends

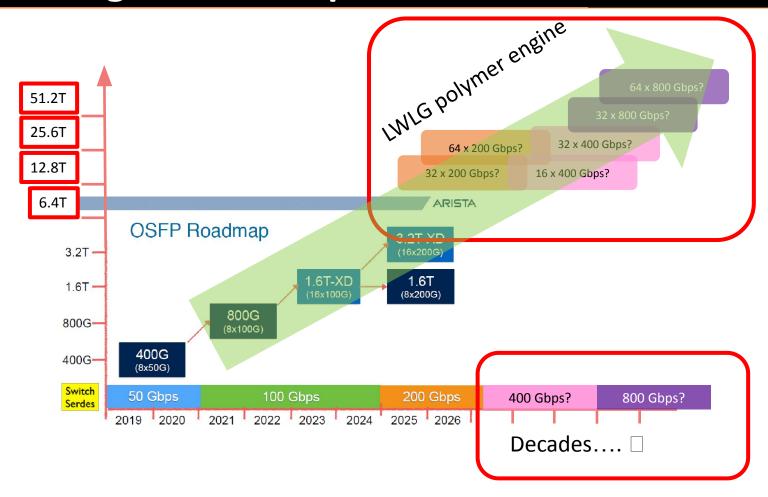




Pluggable transceivers need to increase in speed in conjunction with the electronics

Polymer engine roadmap...

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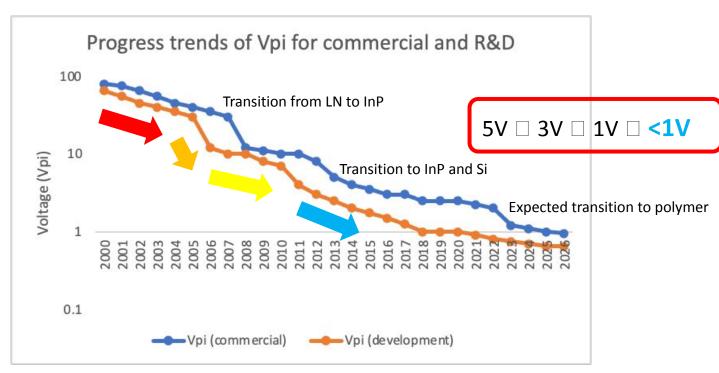
Roadmap enabled by high speed, low power, tiny footprint polymers...

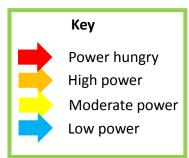


Ultra-low voltage polymers save power...

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- Low voltage polymers ------Modulators can be driven directly from CMOS
- Lower voltage operation ------Saves power (~2-3X at device level)
- Less IC chips/drivers on the line card -----Lowers power and cost (~5-10X at board level)





Commercial progress trails development progress ~5yrs

Transition to polymer is coming as low power issues become dominant



Summary...

Material Science



Standard fabrication & testing



High speed device design & packaging

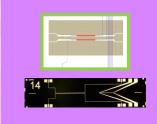


Powerful patent portfolio



Huge \$B markets

Selling components



Licensing polymer materials



Technology transfer (to foundries)



Solving key internet **Achilles Heels**



Volume scale with silicon foundries



Takeaways

- •We have unique polymers...
- •Our technology is *ultra*-fast and *ultra*-low power...
- •We are positioned to have polymers become ubiquitous...
- •Polymers are foundry compatible...

